

SOT882-1

plastic low profile ball grid array package; 260 balls; body 19 x 19 x 1 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LBGA260
Package type industry code	LBGA260
Package style descriptive code	LBGA (low profile ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-192
Mounting method type	S (surface mount)
Issue date	28-2-2005

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		18.8	-	19	19.2	mm
E	package width		18.8	-	19	19.2	mm
A	seated height		[tbd]	-	1.55	1.55	mm
A ₂	package height		0.9	-	1	1.1	mm
n ₂	actual quantity of termination		-	-	260	-	



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2. Package outline

LBGA260: plastic low profile ball grid array package; 260 balls; body 19 x 19 x 1 mm

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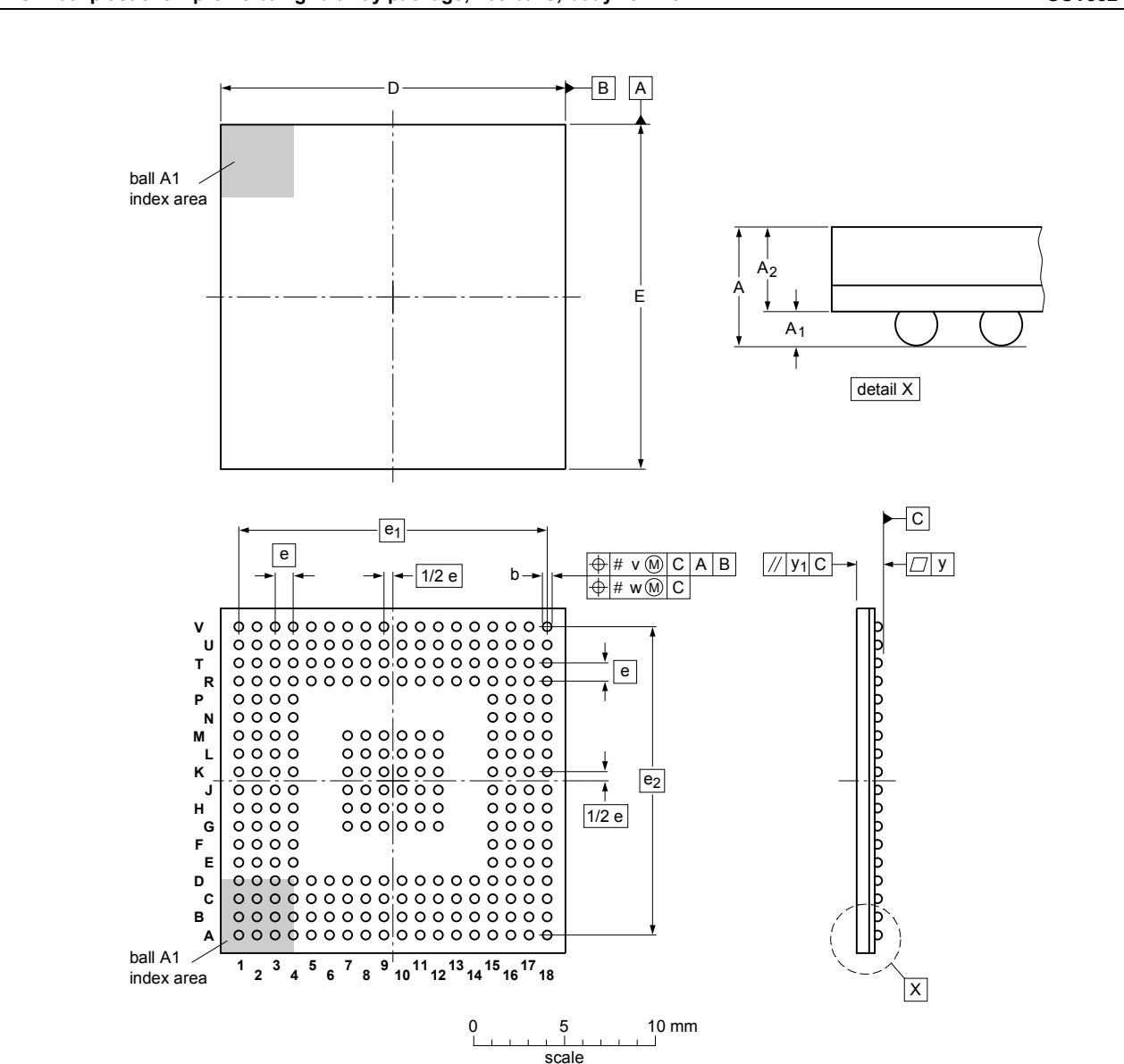


Fig. 1. Package outline LBG260 (SOT882-1)

3. Soldering

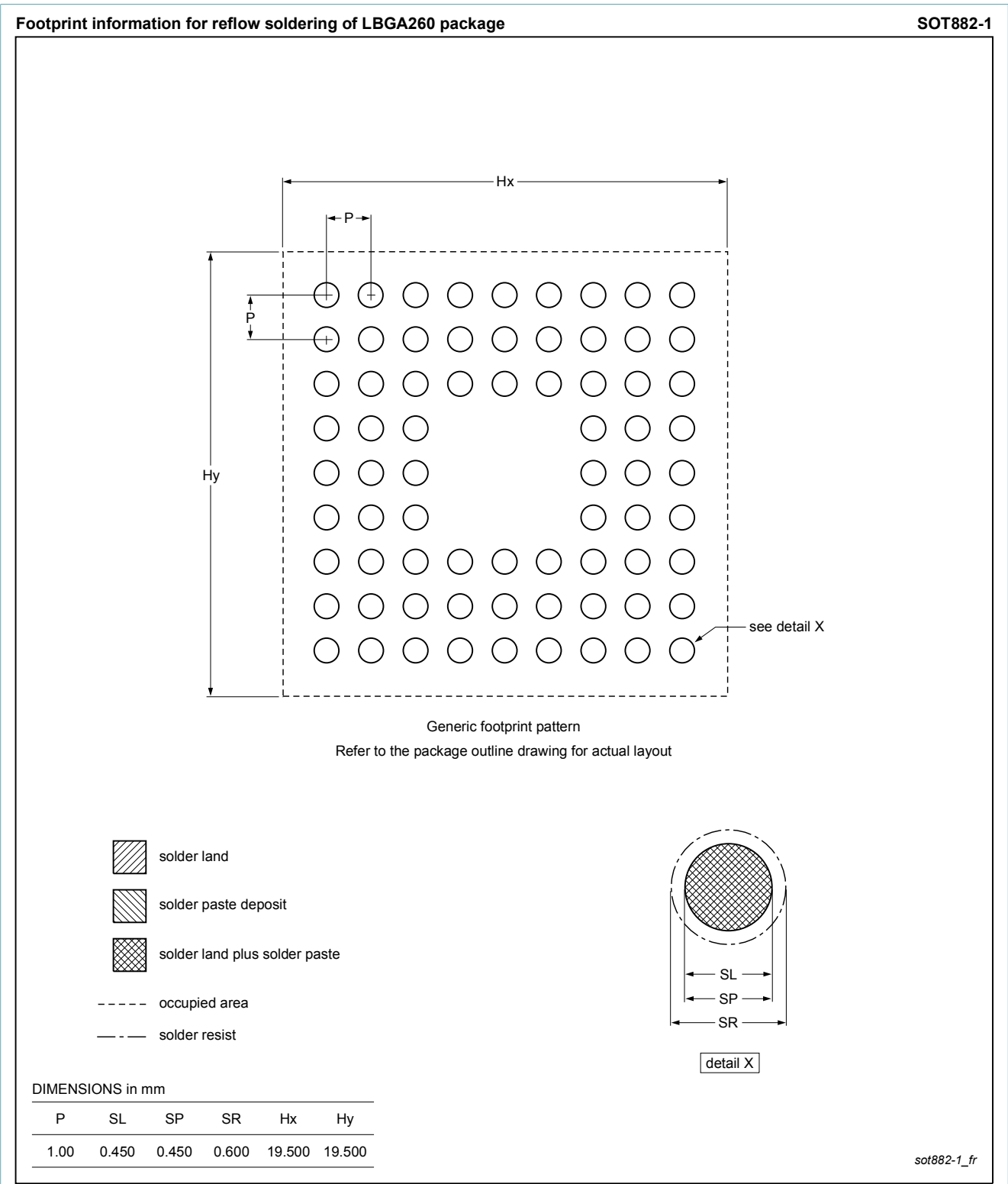


Fig. 2. Reflow soldering footprint for LBGA260 (SOT882-1)

4. Legal information

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